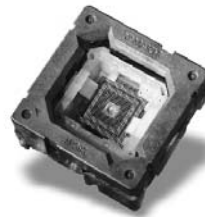


Specifications

Insulation Resistance:	1,000MΩ min. at 100V DC
Dielectric Withstanding Voltage:	100V AC for 1 minute
Contact Resistance:	100mΩ max. at 10mA/20mV max.
Operating Temperature Range:	-40°C to +150°C
Contact Force:	10gf per pin approx.
Operating Force:	2.2kg ±0.5



Part Number (Details)

NP383 - *** 09 *

Series No.

No. of Contact Pins

Design Number

Positioning Pin: N = Without
P = With

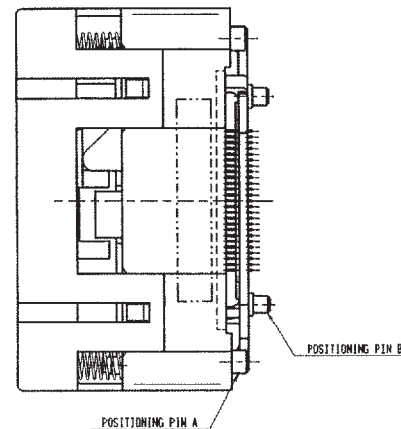
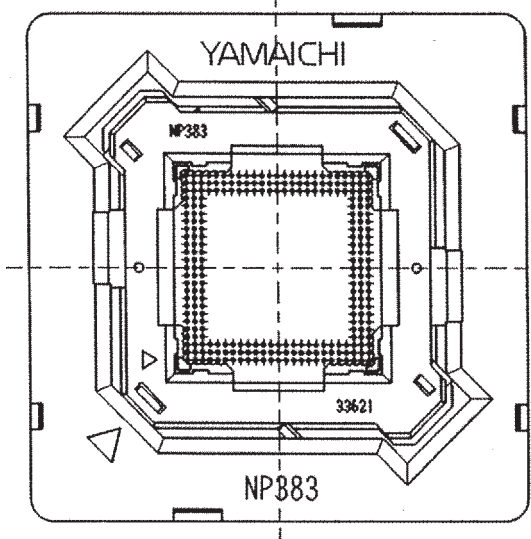
Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
Polyethersulphone (PES), glass-filled
Contacts: Beryllium Copper (BeCu)
Plating: Gold over Nickel

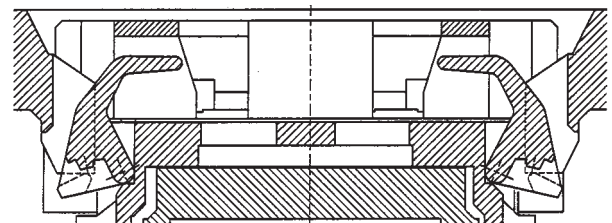
Features

- ⇨ Open top socket for BGA
- ⇨ Through hole 0.5mm pitch
- ⇨ 2-point Tweezer Contacts

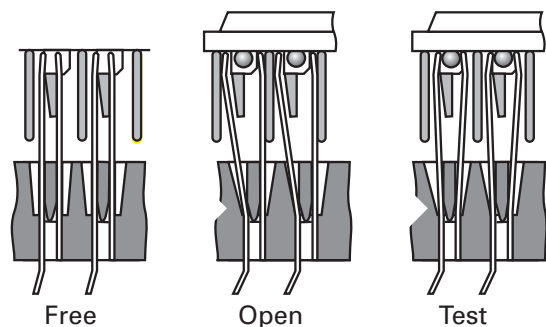
Example Socket Dimensions



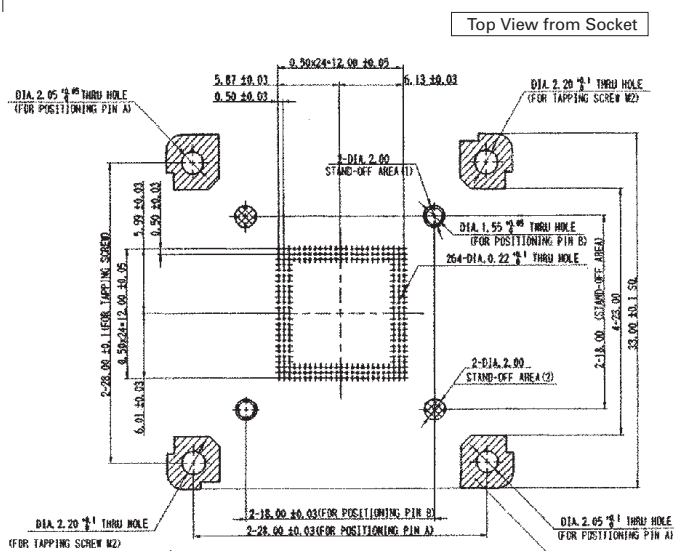
Contact Details



2-point Tweezer Style Contact



Recommended PC Board Layout



Part Number	Grid Size	Body size	Socket Dimensions	Centre Grid size
NP383-18010-*	10x18	11.0x12.5	19.5x26.0	no grid centre
NP383-28804-*	18x18	10.0x10.0	36.0x36.0	6x6
NP383-84107-*	29x29	15.0x15.0	33.0x33	7x7